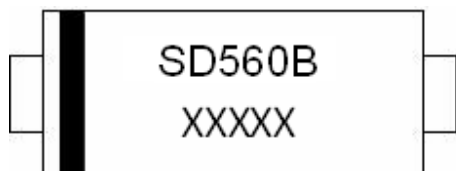


Marking Diagram:

Where XXXXX is YYWWL



SD560B = Part Name
YY = Year
WW = Week
L = Lot Number

Cautions: Molding resin
Epoxy resin UL:94V-0

Ordering Information

Device	Package	Shipping
SD560B	SMB (Pb-Free)	3000pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification.

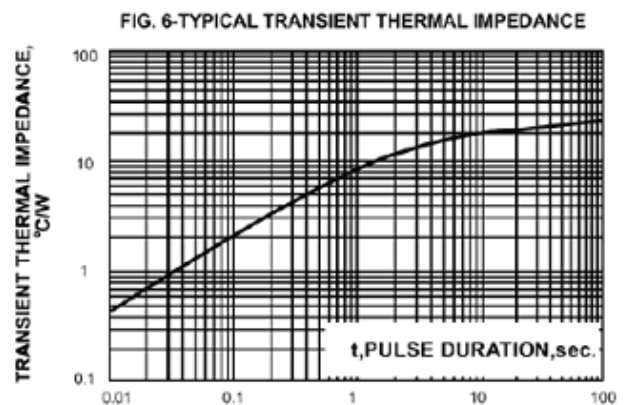
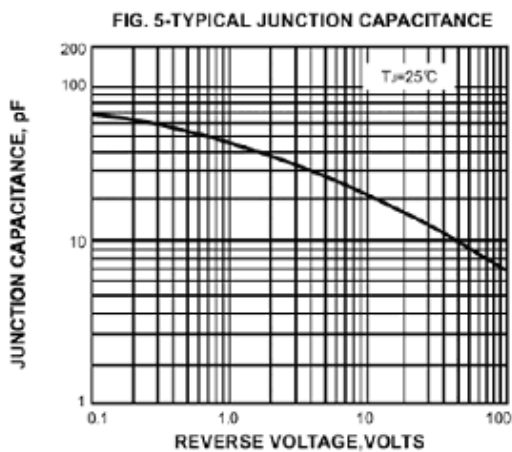
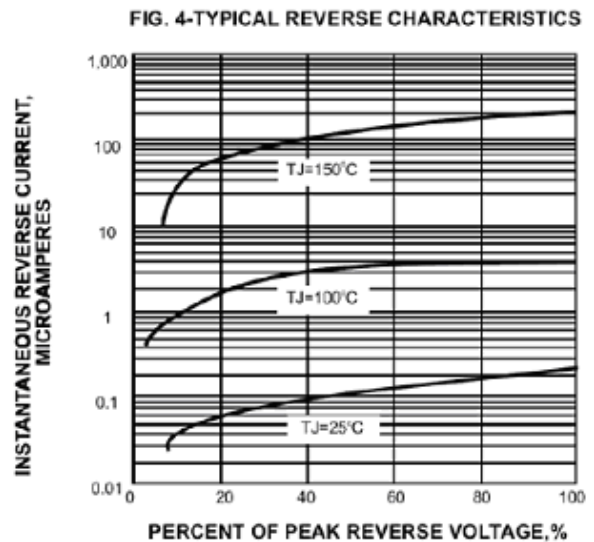
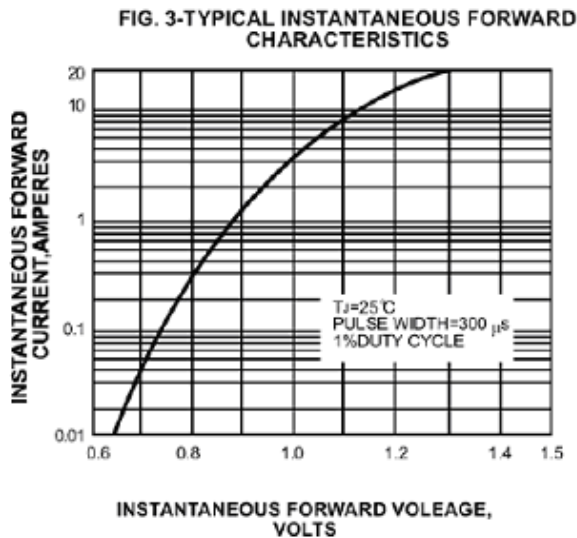
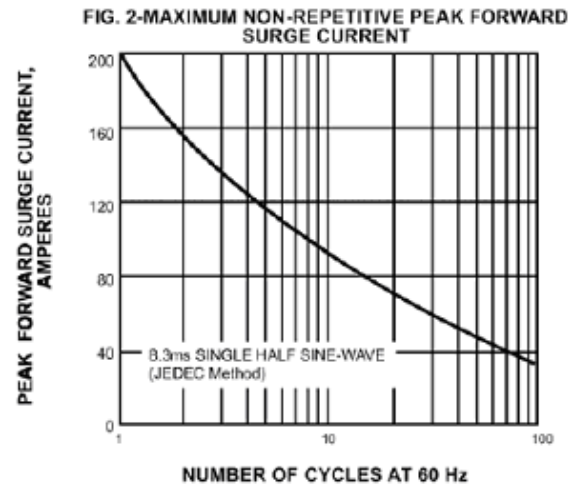
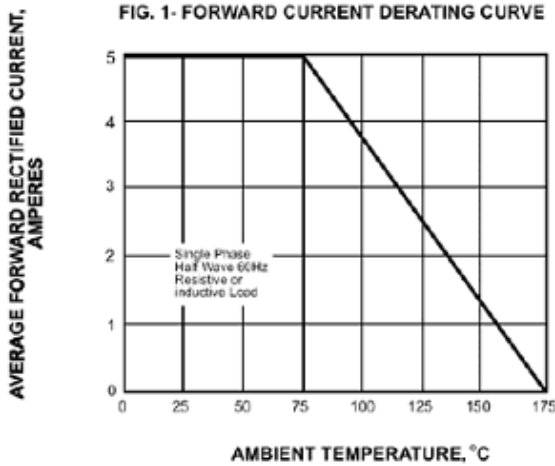
Maximum Ratings and Electrical Characteristics @ $T_A=25^{\circ}\text{C}$ unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.
 For capacitive load, derate current by 20%.

Characteristic	Symbol	SD560B	Unit
Maximum Peak Repetitive Reverse Voltage Maximum DC Blocking Voltage	V_{RRM} V_{DC}	600	V
Maximum RMS Voltage	V_{RMS}	420	V
Maximum Average Forward Rectified Current 0.375"(9.5mm) Lead Length @ $T_A = 75^{\circ}\text{C}$	$I_{(AV)}$	5.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	200	A
$I^2 t$ Rating for fusing ($t < 8.3\text{ms}$)	$I^2 t$	166	$\text{A}^2 \text{S}$
Maximum Instantaneous Forward Voltage @ $I_F = 5.0\text{A}$	V_F	1.2	V
Maximum DC Reverse Current At Rated DC Blocking Voltage	I_R	9.0 170	μA
Typical Junction Capacitance (Note 1)	C_j	50	pF
Typical Thermal Resistance (Note 2)	$R_{\theta JA}$	20	$^{\circ}\text{C}/\text{W}$
Operating Storage Temperature Range	T_{STG}	-65 to +175	$^{\circ}\text{C}$
Operating Junction Temperature	T_J	-65 to +175	$^{\circ}\text{C}$
Case Style	SMB		

Note: 1. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

2. Thermal resistance from junction to ambient at 0.375" (9.5mm) lead length, P.C.B. mounted



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